SN54ACT564, SN74ACT564 OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS

SCAS549B - NOVEMBER 1995 - REVISED NOVEMBER 2002

- 4.5-V to 5.5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 8.5 ns at 5 V
- Inputs Are TTL-Voltage Compatible
- 3-State Inverted Outputs Drive Bus Lines Directly
- Flow-Through Architecture to Optimize PCB Layout
- Full Parallel Access for Loading

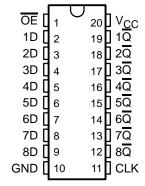
description/ordering information

The 'ACT564 devices are octal D-type edge-triggered flip-flops that feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

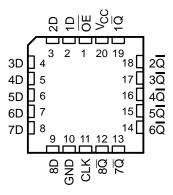
On the positive transition of the clock (CLK) input, the \overline{Q} outputs are set to the complements of the logic levels set up at the data (D) inputs.

A buffered output-enable (\overline{OE}) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

SN54ACT564 . . . J OR W PACKAGE SN74ACT564 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54ACT564 . . . FK PACKAGE (TOP VIEW)



ORDERING INFORMATION

TA	PACKAGE	<u>=</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74ACT564N	SN74ACT564N
	SOIC - DW	Tube	SN74ACT564DW	ACT564
-40°C to 85°C	301C - DW	Tape and reel	SN74ACT564DWR	AC1504
-40 C to 65 C	SOP - NS	Tape and reel	SN74ACT564NSR	ACT564
	SSOP – DB	Tape and reel	SN74ACT564DBR	AD564
	TSSOP – PW	Tape and reel	SN74ACT564PWR	AD564
	CDIP – J	Tube	SNJ54ACT564J	SNJ54ACT564J
–55°C to 125°C	CFP – W	Tube	SNJ54ACT564W	SNJ54ACT564W
	LCCC – FK	Tube	SNJ54ACT564FK	SNJ54ACT564FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

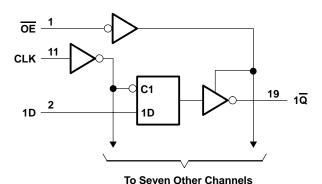
OE does not affect internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE (each flip-flop)

	INPUTS	OUTPUT	
ŌE	CLK	D	Q
L	↑	Н	L
L	\uparrow	L	Н
L	H or L	Χ	\overline{Q}_0
Н	Χ	Χ	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		1.000000000000000000000000000000000000
Output voltage range, VO (see Note 1)		$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)		±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CO}	c)	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	-	±50 mA
Continuous current through V _{CC} or GND		±200 mA
Package thermal impedance, θ _{JA} (see Note 2):	: DB package	70°C/W
	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
	PW package	83°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 3)

		SN54A	CT564	SN74A	CT564	UNIT
		MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
٧ _{IH}	High-level input voltage	2	7	2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
٧ _I	Input voltage	0	Vcc	0	VCC	٧
۷o	Output voltage	0,	Vcc	0	VCC	٧
loh	High-level output current	200	-24		-24	mA
l _{OL}	Low-level output current	70	24		24	mA
Δt/Δν	Input transition rise or fall rate	0	8		8	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COMPITIONS		T,	Δ = 25°C	;	SN54A	CT564	SN74A	CT564	LINUT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	Jan = 50 uA	4.5 V	4.4	4.49		4.4		4.4		
	I _{OH} = -50 μA	5.5 V	5.4	5.49		5.4		5.4		
Vari	lau - 24 mA	4.5 V	3.86			3.7		3.76		V
VOH	I _{OH} = -24 mA	5.5 V	4.86			4.7		4.76		V
	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85	4			
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					7	3.85		
	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	
	ΙΟΣ = 30 μΑ	5.5 V			0.1		0.1		0.1	٧
Va.	le: - 24 mA	4.5 V			0.36	2	0.5		0.44	
VOL	I _{OL} = 24 mA	5.5 V			0.36	⁷ 0,	0.5		0.44	
	I _{OL} = 50 mA [†]	5.5 V				0	1.65			
	I _{OL} = 75 mA [†]	5.5 V							1.65	
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.25		±5		±2.5	μΑ
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		80		40	μΑ
∆I _{CC} ‡	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V		0.6			1.6		1.5	mA
C _i	V _I = V _{CC} or GND	5 V		4.5						pF
Co	V _O = V _{CC} or GND	5 V		15						pF

Thot more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.



[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

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timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			25°C	SN54ACT564	SN74A	CT564	UNIT
		MIN	MAX	MIN MAX	MIN	MAX	UNIT
fclock	Clock frequency		85	65		75	MHz
t _W	Pulse duration, CLK high or low	3		74 B	3.5		ns
t _{su}	Setup time, data before CLK↑	2.5		3.5	3		ns
th	Hold time, data after CLK↑	1		2.5	1		ns

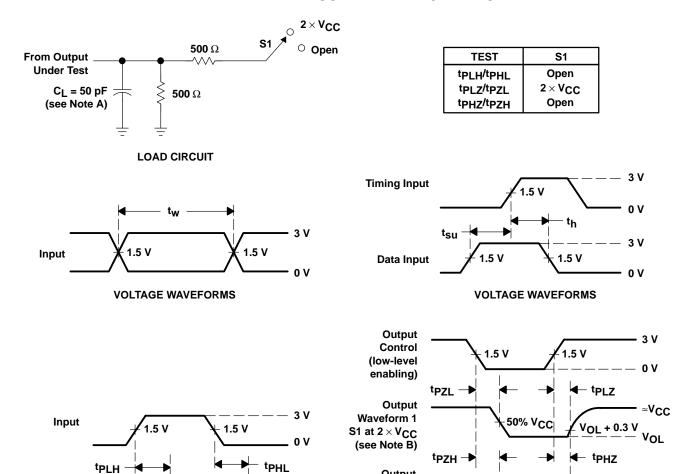
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T,	T _A = 25°C			CT564	SN74A	CT564	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f _{max}			85	90		65	N.	75		MHz
^t PLH	CLK	Ια	2	6.5	10.5	1	12.5	1.5	11.5	20
^t PHL	CLK	Q	1.5	6	9.5	16	11.5	1.5	10.5	ns
^t PZH		Ια	1.5	5.5	9	70	10.5	1.5	9.5	20
^t PZL	ŌĒ	Q	1.5	5.5	8.5	Q 1	10.5	1	9.5	ns
^t PHZ	ŌĒ	Q	1.5	7	10.5	1	12.5	1.5	11.5	no
t _{PLZ}) OE	Q	1.5	5	8	1	9.5	1	8.5	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	TYP	UNIT	
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 1 MHz	50	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

Output

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

VOH

VOL

50% V_CC

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.

Output

Waveform 2

S1 at Open

(see Note B)

D. The outputs are measured one at a time with one input transition per measurement.

50% V_{CC}

VOLTAGE WAVEFORMS

Figure 1. Load Circuit and Voltage Waveforms



V_{OH} – 0.3 V

VOLTAGE WAVEFORMS





10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ACT564DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT564	Samples
SN74ACT564DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT564	Samples
SN74ACT564N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74ACT564N	Samples
SN74ACT564NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT564	Samples
SN74ACT564PW	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD564	Samples
SN74ACT564PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD564	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

10-Dec-2020

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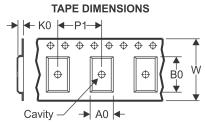
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT564DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ACT564NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74ACT564PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT564DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ACT564NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ACT564PWR	TSSOP	PW	20	2000	853.0	449.0	35.0

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
 C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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